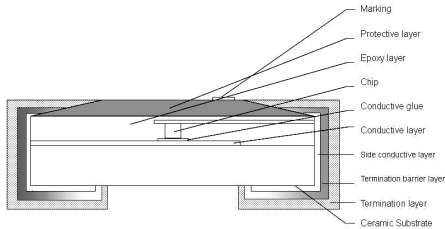


Component Description	Part Number	Total Component Weight in mg	Breakdown of component	Material Name	Substance Name	CAS Number	RoHS Hazardous Substance/ppm						Halogen/ppm				Supplier
							Pb 鉛	Cd 鎘	Hg 汞	Cr6+ 六價鉻	PBBs 多溴聯苯	PBDEs 多溴聯苯醚	F	Cl	Br	I	
Chip Diode, CD4148 series			Substrate	Ceramic	Al2O3	1344-28-1	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	LEATEC
			Conductive layer	Silver paste	Ag	7440-22-4	ND	ND	ND	ND	ND	716	ND	ND	ND	NAMICS	
			Conductive glue	Silver paste	Ag	7440-22-4	ND	ND	ND	ND	ND	ND	ND	ND	ND	NAMICS	
			Diode Chip	Silicon	Si	7631-86-9	ND	ND	ND	ND	ND	ND	ND	ND	ND	Phenitec	
			Epoxy layer	Silicon Dioxide	SiO2	7631-86-9	ND	ND	ND	ND	ND	ND	105	ND	ND	Ever Bright	
			Protective layer	Epoxy	Epoxy	trade scretre	ND	ND	ND	ND	ND	85	516	ND	ND	TAIYO	
			Marking	Epoxy	Epoxy	trade scretre	ND	ND	ND	ND	ND	ND	753	ND	ND	CHUNG YU	
			Side conductive layer	Silver paste	Ag	7440-22-4	ND	ND	ND	ND	ND	ND	ND	ND	ND	NAMICS	
			Termination barrier layer	Nickel	Ni	7440-02-0	ND	ND	ND	ND	ND	ND	ND	ND	ND	INCO	
			Termination layer	Tin	Sn	7440-31-5	48	ND	ND	ND	ND	-	-	-	-	ELECTROLOY	



Chip Switching Diode CD4148 Series Material Declaration

美隆電子有限公司
 深圳市美科達實業發展有限公司

已審核

Mayloon Peter Lau 09/02/25, 12:17



品質承諾標誌
 Quality Commitment

